# MOS INTEGRATED CIRCUIT $\mu \mathbf{PD4724}$

# RS-232 LINE DRIVER/RECEIVER AT 3.3 V/5 V

The  $\mu$ PD4724 is a high breakdown voltage silicon gate CMOS line driver/receiver based on the EIA/TIA-232-E standard. This IC features various functions, such as standby, and incorporates a DC/DC converter that switches boost multiples, enabling operation at both +3.3 V and +5 V single supply voltage.

The  $\mu$ PD4724 incorporates three drivers and five receivers, so an RS-232 interface circuit can be easily constructed by connecting five external capacitors.

#### FEATURES

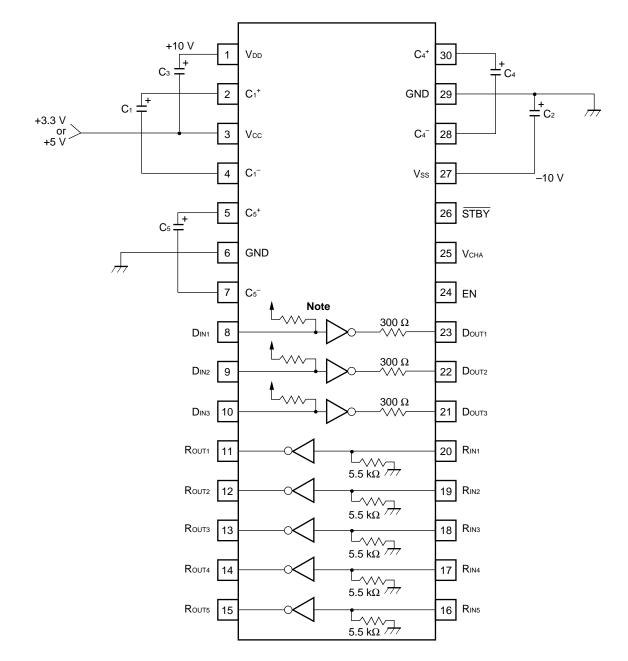
NEC

- Based on EIA/TIA-232-E (RS-232-C) standard.
- Single power supply: +3.3 V or +5 V (selectable with the VCHA pin)
- Standby mode: Setting the standby pin to low level switches this IC into the standby mode and makes the driver outputs high-impedance.
- Enable mode: When the enable pin is high level during the standby mode, two receivers can operate as inverters without hysteresis width (The other three receivers are fixed to high level).

#### **ORDERING INFORMATION**

Part number	Package
μPD4724GS-GJG	30-pin plastic shrink SOP (300 mil)

#### **BLOCK DIAGRAM/PIN CONFIGURATION (TOP VIEW)**



Note The pull-up resistors of the driver inputs are active resistors.

- **Remark 1.** VDD and Vss are pins that output the voltage boosted internally. Don't connect these pins to the load.
  - 2. Capacitors with a breakdown voltage of 20 V or higher are recommended for C<sub>1</sub> to C<sub>5</sub>. And it is recommended to insert the capacitor that is 0.1  $\mu$ F to 1  $\mu$ F between Vcc and GND.
  - **3.** The capacitor C<sub>5</sub> does not have to be connected when the IC is used in 5 V mode (V<sub>CHA</sub> = L).

## TRUTH TABLE

Driver

STBY	Din	Dout	Remark
L	×	Z	Standby mode (D/D converter OFF)
н	L	Н	Space level output
н	Н	L	Mark level output

## Receiver

		R	IN	Ro	UT	Demorte
STBY	BY EN R4 to R5 R1 to R3 R4 to R5 R1 to		R1 to R3	Remark		
L	L	×	×	нн		Standby mode1 (D/D converter OFF)
L	н	L	×	нн		Standby mode2 (D/D converter OFF, R4 and R5 operate)
L	н	н	×	L	Н	Standby mode2 (D/D converter OFF, $R_4$ and $R_5$ operate)
н	×	L	-	Н		Mark level input
н	×	ŀ	H L		_	Space level input

# 3 V and 5 V Switching<sup>Note</sup>

Vсна	Operation mode
L	5 V mode (Double boost)
н	3 V mode (Triple boost)

H: High level, L: Low level, Z: High-impedance, ×: Don't care

**Note** Be sure to switch the V<sub>CHA</sub> pin in standby mode ( $\overline{\text{STBY}}$  = L).

#### ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = +25 $^{\circ}$ C)

Parameter	Symbol	Ratings	Unit
Supply Voltage (VCHA = L)	Vcc	-0.5 to +7.0	V
Supply Voltage (V <sub>CHA</sub> = H)	Vcc	-0.5 to +4.5	V
Driver Input Voltage	Din	-0.5 to Vcc + 0.5	V
Receiver Input Voltage	Rin	-30.0 to +30.0	V
Control Input Voltage (STBY, VCHA, EN)	Vin	-0.5 to Vcc + 0.5	V
Driver Output Voltage	Dout	-25.0 to +25.0 <sup>Note</sup>	V
Receiver Output Voltage	Rout	-0.5 to Vcc + 0.5	V
Input Current (DIN, STBY, VCHA, EN)	Іім	±20.0	mA
Operating Temperature	TA	-40 to +85	°C
Storage Temperature	Tstg	-55 to +150	°C
Power Dissipation	Рт	0.5	W

**Note** Pulse width = 1 ms, duty cycle = 10 % MAX.

#### **RECOMMENDED OPERATING CONDITIONS**

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply Voltage (VCHA = L, 5 V mode)	Vcc	4.5	5.0	5.5	V
Supply Voltage (VCHA = H, 3 V mode)	Vcc	3.0	3.3	3.6	V
High Level Input Voltage (DIN)	Vін	2.0		Vcc	V
Low Level Input Voltage (DIN)	VIL	0		0.8	V
High Level Input Voltage (STBY, VCHA, EN)	Vін	2.4		Vcc	V
Low Level Input Voltage (STBY, VCHA, EN)	VIL	0		0.6	V
Receiver Input Voltage	RIN	-30		+30	V
Operating Temperature	TA	-40		+85	°C
Capacitance of External Capacitor	Note	0.33		4.7	μF

**Note** If the use of an electrolytic capacitor at low temperature is likely, set the capacitance with sufficient margin, because the capacitance of an electrolytic capacitor is smaller at lower temperatures (0 °C or lower). Care must be taken to minimize the wiring length between the capacitor and this IC. Using capacitors of excellent high frequency characteristics (such as tantalum, multi-layer ceramic capacitors, and aluminum electrolytic capacitors for switching power supplies) is highly recommended.

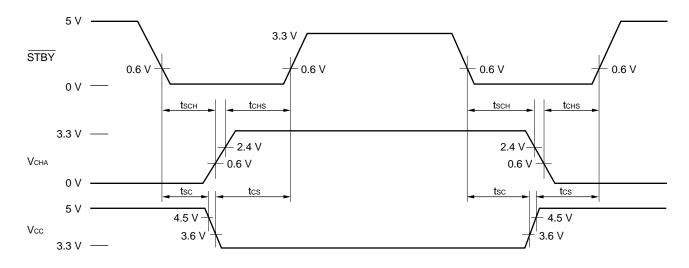
# ELECTRICAL SPECIFICATIONS FOR THE IC AS A WHOLE

$(T_A = -40 \text{ to } +85 ^\circ)$	C and C1 to C5 =	1 $\mu$ F Unless	<b>Otherwise Specified)</b>
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Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Circuit Current	lasi	$\frac{V_{CC} = +3.3 \text{ V}, \text{ unloaded}, \text{ R}_{\text{IN}} \text{ pin is open},}{\text{STBY}} = \text{H}$		7.5	15	mA
Circuit Current	Icc1	$V_{CC}$ = +5.0 V, unloaded, R <sub>IN</sub> pin is open, STBY = H		5.5	11	mA
Circuit Current		$\label{eq:Vcc} \begin{array}{l} V_{CC} = +3.3 \ V, \ R_L = 3 \ k \Omega(D_{OUT}), \ D_{IN} = GND, \\ R_{IN} \ and \ R_{OUT} \ pins \ are \ open, \ \overline{STBY} = H \end{array}$		25	35	mA
Circuit Current	Icc2	$\label{eq:Vcc} \begin{array}{l} V_{\text{Cc}} = +5.0 \text{ V}, \text{ RL} = 3  \text{k} \Omega(\text{Dout}),  \text{Din} = \text{GND}, \\ \text{R}_{\text{IN}} \text{ and } \text{R}_{\text{OUT}} \text{ pins are open}, \end{tabular} \begin{array}{l} \text{STBY} = \text{H} \end{array}$		19	28	mA
Circuit Current at Standby		$V_{CC}$ = +3.3 V, No load, DIN and RIN pins are OPEN, $\overline{STBY}$ = L, EN = L, TA = 25 °C		1	3	μA
		$V_{CC}$ = +3.3 V, No load, DIN and RIN pins are OPEN, STBY = L, EN = L		5		μA
(Standby Mode 1)	Іссз	$V_{CC} = +5.0 \text{ V}$ , No load, DIN and RIN pins are OPEN, $\overline{\text{STBY}} = \text{L}$ , EN = L, TA = 25 °C		2	5	μA
		$V_{CC}$ = +5.0 V, No load, DIN and RIN pins are OPEN, STBY = L, EN = L		10		μA
Circuit Current at Standby		$V_{CC}$ = +3.3 V, No load, DIN and RIN pins are OPEN, $\overline{STBY}$ = L, EN = H, TA = 25 °C		1	3	μΑ
		$V_{CC}$ = +3.3 V, No load, DIN and RIN pins are OPEN, STBY = L, EN = H		5		μΑ
(Standby Mode 2)	Icc4	$V_{CC}$ = +5.0 V, No load, D <sub>IN</sub> and R <sub>IN</sub> pins are OPEN, STBY = L, EN = H, TA = 25 °C		2	5	μΑ
		$V_{CC}$ = +5.0 V, No load, DIN and RIN pins are OPEN, STBY = L, EN = H		10		μΑ
High Level Input Voltage	Vін	Vcc = +3.0 to +5.5 V, $\overline{\text{STBY}}$ , VcHA, and EN pins	2.4			V
Low Level Input Voltage	VIL	Vcc = +3.0 to +5.5 V, $\overline{\text{STBY}}$ , VcHA, and EN pins			0.6	V
High Level Input Current	Ін	$V_{CC} = +5.5 \text{ V}, \text{ V}_{I} = +5.5 \text{ V}, \overline{\text{STBY}}, \text{ V}_{CHA}, \text{ and}$ EN pins			1	μΑ
Low Level Input Current	II.	$V_{CC} = +5.5 \text{ V}, \text{ V}_{I} = 0 \text{ V}, \overline{\text{STBY}}, \text{V}_{CHA}, \text{ and} \text{ EN pins}$			-1	μA
		Driver and receiver inputs, $V_{CC} = +3.3$ V, to GND, f = 1 MHz			10	pF
Input Capacitance	Cin	Driver and receiver inputs, Vcc = +5.0 V, to GND, f = 1 MHz			10	pF
STBY - VCHA Time	tscн	$V_{\text{CC}} = +3.0 \text{ to } +5.5 \text{ V}, \overline{\text{STBY}} \downarrow \rightarrow V_{\text{CHA}} ^{\text{Note}}$	1			μs
VCHA - STBY Time	tснs	$V_{\text{CC}} = +3.0 \text{ to } +5.5 \text{ V}, \text{V}_{\text{CHA}} \rightarrow \overline{\text{STBY}} \uparrow \text{Note}$	1			μs
STBY - Vcc Time	tsc	Vcc = +3.0 to +5.5 V, $\overline{\text{STBY}} \downarrow \rightarrow \text{Vcc}^{\text{Note}}$	1			μs
Vcc - STBY Time	tcs	$V_{\text{CC}} = +3.0 \text{ to } +5.5 \text{ V}, \text{ V}_{\text{CC}} \rightarrow \overline{\text{STBY}} \uparrow \text{Note}$	1			μs

**Remark** TYP. values are valid only at  $T_A = 25 \ ^\circ C$  and should be used for reference only.

# Note Test points for these parameters



#### ELECTRICAL SPECIFICATIONS FOR THE DRIVERS (TA = -40 to +85 °C and C1 to C5 = 1 $\mu$ F)

#### 3 V Mode (VCHA = H, Vcc = 3.0 to 3.6 V Unless Otherwise Specified)

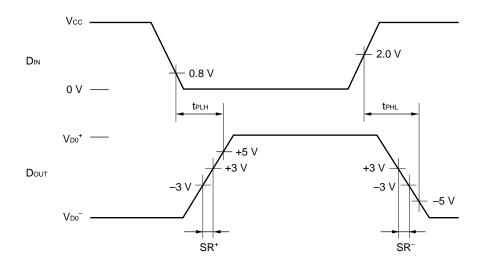
Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Low Level Input Voltage	VIL				0.8	V
High Level Input Voltage	Vін		2.0			V
Low Level Input Current	lı.	Vcc = +3.6 V, VI = 0 V			-25	μA
High Level Input Current	Ін	Vcc = +3.6 V, VI = 3.6 V			1.0	μA
Output Voltage		$V_{CC} = +3.3 \text{ V}, \text{ R}_{L} = \infty, \text{ T}_{A} = 25 ^{\circ}\text{C}$		±9.5		V
	Vdo	$V_{CC} = +3.3 \text{ V}, \text{ R}_{\text{L}} = 3 \text{ k}\Omega, \text{ T}_{\text{A}} = \text{T}_{\text{opt.}}$	±5.0	±6.0		V
		Vcc = +3.0 V, RL = 3 k $\Omega$ , TA = 25 °C	±5.0			V
Output Short-Circuit Current	Isc	Vcc = +3.3 V, to GND			±40	mA
Slew Rate <sup>Note 1</sup>	SR	$C_L$ = 10 pF, $R_L$ = 3 to 7 k $\Omega$	3.0		30	V/µs
Siew Rate		$C_{\text{L}}$ = 2500 pF, R_{\text{L}} = 3 to 7 k $\Omega$	3.0		30	V/µs
Propagation Delay Time <sup>Note 1</sup>	tрні tplh	$R_L = 3 \ k\Omega, \ C_L = 2500 \ pF$		2.5		μs
Output Resistance	Ro	$V_{CC} = V_{DD} = V_{SS} = 0 V$ $V_{OUT} = \pm 2 V$	300			Ω
Output Transfer Time in Standby State	tdaz	$R_L = 3 \text{ k}\Omega, C_L = 2500 \text{ pF}, \text{Note 2}$		4	10	μs
Output Transfer Time in Standby State	<b>t</b> dza	$R_{L} = 3 \text{ k}\Omega, C_{L} = 2500 \text{ pF}, \text{Note 2}$		1	3	ms
Power On Output Transfer Time	<b>t</b> PRA	$R_{L} = 3 \text{ k}\Omega, C_{L} = 2500 \text{ pF}, \text{Note } 3$		1	3	ms

**Remark** TYP. values are valid only at  $T_A = 25 \text{ °C}$  and should be used for reference only.

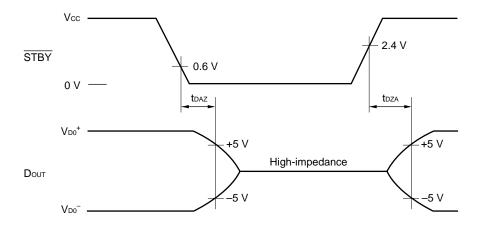
Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Low Level Input Voltage	VIL				0.8	V
High Level Input Voltage	Vін		2.0			V
Low Level Input Current	lı∟	$Vcc = +5.5 V, V_1 = 0 V$			-40	μA
High Level Input Current	Ін	Vcc = +5.5 V, VI = 5.5 V			1.0	μA
Output Voltage		Vcc = +5.0 V, $R_L = \infty$ , $T_A = 25 \ ^{\circ}C$		±9.7		V
	Vdo	$V_{CC} = +5.0 \text{ V},  \text{R}_{\text{L}} = 3  \text{k}\Omega,  \text{T}_{\text{A}} = \text{T}_{\text{opt.}}$	±6.0			V
		Vcc = +4.5 V, R <sub>L</sub> = 3 k $\Omega$ , T <sub>A</sub> = T <sub>opt</sub> .	±5.0			V
Output Short-Circuit Current	Isc	Vcc = +5.0 V, to GND			±40	mA
Slew Rate <sup>Note 1</sup>	SR	$C_L$ = 10 pF, $R_L$ = 3 to 7 k $\Omega$	4.0		30	V/µs
Siew Rale		$C_L$ = 2500 pF, $R_L$ = 3 to 7 k $\Omega$	4.0		30	V/µs
Propagation Delay Time <sup>Note 1</sup>	tрні tplh	$R_L = 3 \text{ k}\Omega, C_L = 2500 \text{ pF}$		2		μs
Output Resistance	Ro	$V_{CC} = V_{DD} = V_{SS} = 0 V$ $V_{OUT} = \pm 2 V$	300			Ω
Output Transfer Time in Standby State	<b>t</b> daz	$R_L = 3 \text{ k}\Omega, C_L = 2500 \text{ pF}, \text{Note 2}$		4	10	μs
Output Transfer Time in Standby State	<b>t</b> dza	$R_L = 3 \text{ k}\Omega, C_L = 2500 \text{ pF}, \text{Note 2}$		0.5	1	ms
Power-On Output Transfer Time	<b>t</b> pra	$R_L = 3 \text{ k}\Omega, C_L = 2500 \text{ pF}, \text{Note 2}$		0.5	1	ms

**Remark** TYP. values are valid only at  $T_A = 25$  °C and should be used for reference only.

Note 1 Test points for slew rate, tPHL, and tPLH

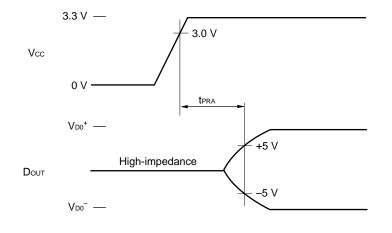






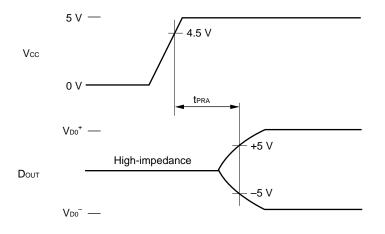
Driver outputs are indefinite during transition time (tDZA).

Note 3 Test points for tPRA in 3 V mode



Driver outputs are indefinite during transition time (tpra).

Note 4 Test points for tPRA in 5 V mode



Driver outputs are indefinite during transition time (tpra).

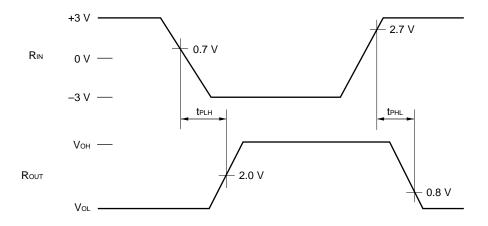
#### ELECTRICAL SPECIFICATIONS FOR THE RECEIVERS

## (Vcc = 3.0 to 5.5 V, T<sub>A</sub> = -40 to +85 °C and C<sub>1</sub> to C<sub>5</sub> = 1 $\mu$ F Unless Otherwise Specified)

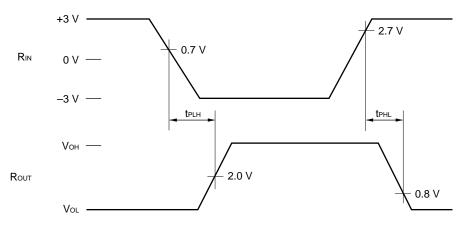
Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Low Level Output Voltage	Vol1	louτ = 4 mA			0.4	V
High Level Output Voltage	Vон1	louт = -4 mA	Vcc-0.4			V
Low-Level Output Voltage	Vol2	Ιουτ = 4 mA, STBY = L			0.5	V
High Level Output Voltage	Vон2	$I_{OUT} = -4 \text{ mA}, \overline{\text{STBY}} = L$	Vcc-0.5			V
Propagation Delay Time (STBY = H)	tрні tplh	$ \begin{array}{l} R_{\text{IN}} \rightarrow R_{\text{OUT}}, \ CL = 150 \ pF \\ V_{\text{CC}} = +3.0 \ V, \\ \end{array} $		0.2		μs
Propagation Delay Time (STBY = L)	tрні tplh	$ \begin{array}{l} R_{\text{IN}} \rightarrow R_{\text{OUT}}, \ CL = 150 \ pF \\ V_{\text{CC}} = +3.0 \ V, \\ \textbf{Note 2} \end{array} $		0.1		μs
Propagation Delay Time (STBY = L)	tрна tран	$\begin{array}{l} EN \rightarrow Rout, \ CL = 150 \ pF \\ Vcc = +3.0 \ V, \\ Note 3 \end{array}$		100	300	ns
Input Resistance	Ri		3	5.5	7	kΩ
Input Terminal Release Voltage	Vio				0.5	V
	Vін	Vcc = +3.0 to + 5.5 V	1.7	2.3	2.7	V
Input Threshold Voltage	VIL	Vcc = +3.0 to + 5.5 V	0.7	1.1	1.7	V
(STBY = H)	Vн	Vcc = +3.0 to + 5.5 V (Hysteresis width)	0.5	1.2	1.8	V
Input Threshold Voltage	Vін	Vcc = +3.0 to + 5.5 V	2.7	1.5		V
(STBY = L, EN = H)	VIL	Vcc = +3.0 to + 5.5 V		1.5	0.7	V
Output Transition Time in Standby State	tdah	Note 4		0.2	3	μs
Output Transition Time in Standby State	<b>t</b> DHA	VCHA = H (3 V mode), Note 4		0.6	3	ms
	UNA	VCHA = L (5 V mode), Note 4		0.3	1	ms
Power-On Reset Release Time	<b>t</b> PRA	VCHA = H (3 V mode), Note 5		1	3	ms
	LPKA	VCHA = L (5 V mode), Note 6		0.5	1	ms

**Remark** TYP. values are valid only at  $T_A = 25$  °C and should be used for reference only.

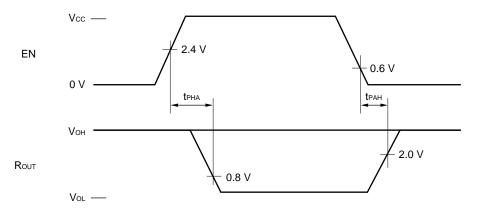
Note 1 Test points for tPHL, tPLH

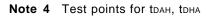


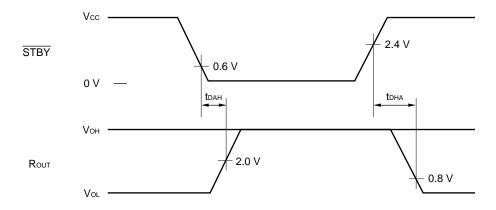
Note 2 Test points for tPHL, tPLH



Note 3 Test points for tPHA, tPAH

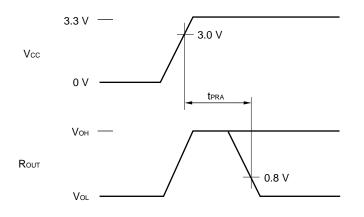






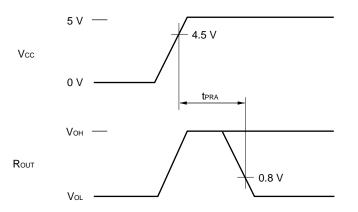
Receiver outputs are indefinite during transition time (tDHA).

Note 5 Test points for tPRA in 3 V mode



Receiver outputs are indefinite during reset release time (tPRA).

Note 6 Test points for tPRA in 5 V mode



Receiver outputs are indefinite during reset release time (tPRA).

#### **REFERENCE MATERIAL**

- IC PACKAGE MANUAL (C10943X)
- NEC SEMICONDUCTOR DEVICE RELIABILITY/QUALITY (IEI-1212)

#### **RECOMMENDED SOLDERING CONDITIONS**

The following conditions (see table below) must be met when soldering this product. Please consult with our sales offices in case other soldering process is used, or in case soldering is done under different conditions.

#### TYPES OF SURFACE MOUNT DEVICE

For more details, refer to our document "SMT MANUAL" (C10535E).

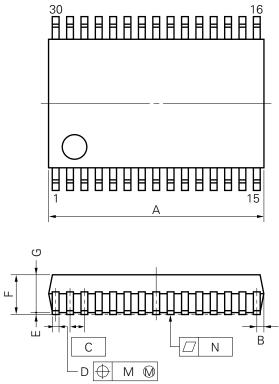
#### $\mu$ PD4724GS-GJG

Soldering process	Soldering conditions	Symbol
Infrared ray reflow	Peak package's surface temperature: 230 °C or below, Reflow time: 30 seconds or below (210 °C or higher), Number of reflow process: 2, Exposure limit*: None	IR30-00-2
VPS	Peak package's surface temperature: 215 °C or below, Reflow time: 40 seconds or below (200 °C or higher), Number of reflow process: 2, Exposure limit*: None	VP15-00-2
Wave soldering	Solder temperature: 260 °C or below, Flow time: 10 seconds or below, Number of flow process: 1, Exposure limit*: None	WS60-00-1
Partial heating method	Terminal temperature: 300 °C or below, Flow time: 10 seconds or below, Exposure limit*: None	0

\* Exposure limit before soldering after dry-pack package is opened. Sotrage conditions: 25 °C and relative humidity at 65 % or less.

Note Do not apply more than a single process at once, except for "Partial heating method".

# 30 PIN PLASTIC SHRINK SOP (300 mil)

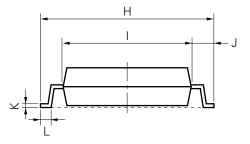


#### ΝΟΤΕ

Each lead centerline is located within 0.10 mm (0.004 inch) of its true position (T.P.) at maximum material condition.

detail of lead end





P30GS-65-300B-1

ITEM	MILLIMETERS	INCHES
А	10.11 MAX.	0.398 MAX.
В	0.51 MAX.	0.020 MAX.
С	0.65 (T.P.)	0.026 (T.P.)
D	$0.30^{+0.10}_{-0.05}$	$0.012\substack{+0.004\\-0.003}$
E	0.125±0.075	0.005±0.003
F	2.0 MAX.	0.079 MAX.
G	1.7±0.1	0.067±0.004
Н	8.1±0.2	0.319±0.008
Ι	6.1±0.2	0.240±0.008
J	1.0±0.2	0.039 <sup>+0.009</sup>
К	$0.15\substack{+0.10 \\ -0.05}$	$0.006^{+0.004}_{-0.002}$
L	0.5±0.2	0.020+0.008
М	0.10	0.004
Ν	0.10	0.004

[MEMO]

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- Standard: Computers, office equipment, communications equipment, test and measurement equipment, audio and visual equipment, home electronic appliances, machine tools, personal electronic equipment and industrial robots
- Special: Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support)
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Anti-radioactive design is not implemented in this product.